

Please note that Cypress is an Infineon Technologies Company.

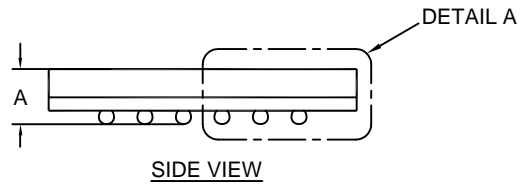
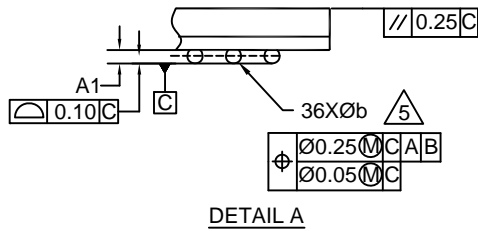
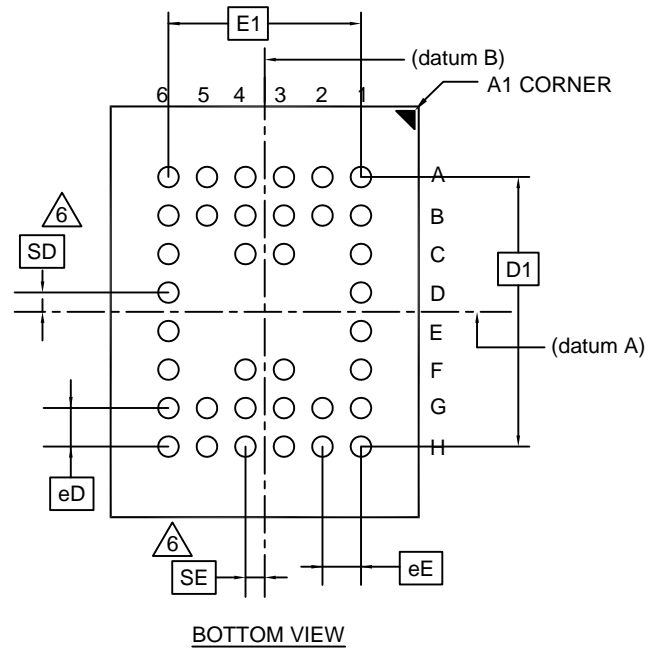
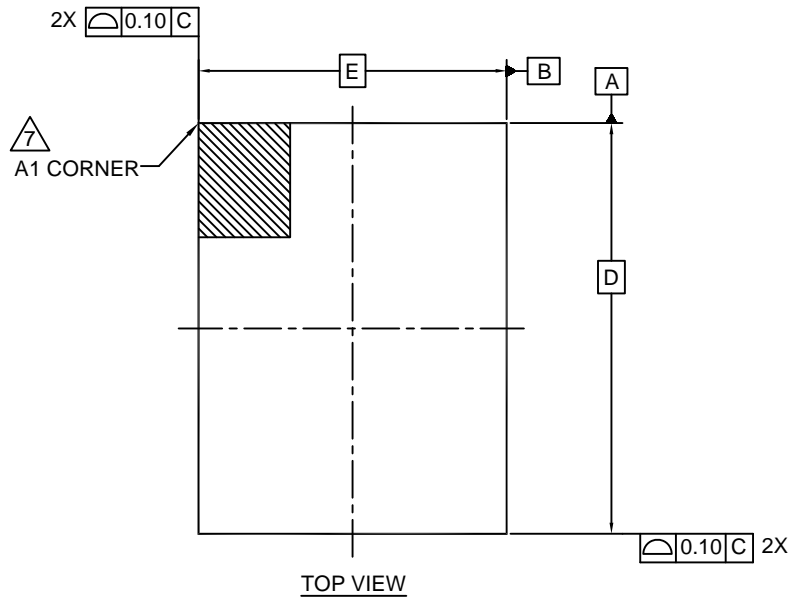
The document following this cover page is marked as “Cypress” document as this is the company that originally developed the product. Please note that Infineon will continue to offer the product to new and existing customers as part of the Infineon product portfolio.

Continuity of document content

The fact that Infineon offers the following product as part of the Infineon product portfolio does not lead to any changes to this document. Future revisions will occur when appropriate, and any changes will be set out on the document history page.

Continuity of ordering part numbers

Infineon continues to support existing part numbers. Please continue to use the ordering part numbers listed in the datasheet for ordering.



SYMBOL	DIMENSIONS		
	MIN.	NOM.	MAX.
A	-	-	1.00
A1	0.16	-	-
D	8.00 BSC		
E	6.00 BSC		
D1	5.25 BSC		
E1	3.75 BSC		
MD	8		
ME	6		
N	36		
Ø b	0.25	0.30	0.35
eD	0.75 BSC		
eE	0.75 BSC		
SD	0.375 BSC		
SE	0.375 BSC		

NOTES:

- ALL DIMENSIONS ARE IN MILLIMETERS.
- SOLDER BALL POSITION DESIGNATION PER JEP95, SECTION 3, SPP-020.
- "e" REPRESENTS THE SOLDER BALL GRID PITCH.
- SYMBOL "MD" IS THE BALL MATRIX SIZE IN THE "D" DIRECTION. SYMBOL "ME" IS THE BALL MATRIX SIZE IN THE "E" DIRECTION. N IS THE NUMBER OF POPULATED SOLDER BALL POSITIONS FOR MATRIX SIZE MD X ME.
- DIMENSION "b" IS MEASURED AT THE MAXIMUM BALL DIAMETER IN A PLANE PARALLEL TO DATUM C.
- "SD" AND "SE" ARE MEASURED WITH RESPECT TO DATUMS A AND B AND DEFINE THE POSITION OF THE CENTER SOLDER BALL IN THE OUTER ROW WHEN THERE IS AN ODD NUMBER OF SOLDER BALLS IN THE OUTER ROW "SD" OR "SE" = 0. WHEN THERE IS AN EVEN NUMBER OF SOLDER BALLS IN THE OUTER ROW "SD" = eD/2 AND "SE" = eE/2.
- A1 CORNER TO BE IDENTIFIED BY CHAMFER, LASER OR INK MARK METALIZED MARK, INDENTATION OR OTHER MEANS.
- "+" INDICATES THE THEORETICAL CENTER OF DEPOPULATED SOLDER BALLS.

REVISIONS			
Rev	ECN No.	Orig. of change	Reason for Revision
**	111202	-	NEW RELEASE
*A	118364	-	CHG. PKG. BODY TOLERANCE/ADD MOLD CAP & SUBSTRATE DIM./CHG. LEAD COPLANARITY & BALL HEIGHT
*B	121986	-	CHG. MOLD CAP DIM. & SUBSTRATE DIM./CHG. TITLE
*C	391420	-	CHG. COPLANARITY FROM 0.15 TO 0.10
*D	2812922	-	Change Template and title from 36 VFBGA (6x8x1.0MM) PACKAGE OUTLINE to PACKAGE OUTLINE, 36L VFBGA 6X8X1.0 MM BV36A.
*E	3313142	-	NO CHANGE. SUNSET REVIEW.
*F	4614873	XANC	FOR SUNSET REVIEW. UPDATE DRAWING TEMPLATE.
*G	5099146	KOTA	CHANGE TO NEW FORMAT DRAWING TEMPLATE. ADD NEW PACKAGE VCF036.



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TITLE PACKAGE OUTLINE, 36 BALL VFBGA
8.0X6.0X1.0 MM VCF036/BV36/BZ36/BZ36A

SPEC NO. 51-85149

SCALE : TO FIT

SHEET 2 OF 2

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PACKAGE CODE(S)
BV36
BZ36
BZ36A
VCF036

DRAWN BY
KOTA
DATE
21-JAN-16
APPROVED BY
CS
DATE
21-JAN-16

REV
*G